


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A


SOLDER MASK OVER BARE COPPER: ELECTROLESS NICKEL IMMERSION GOLD (ENIG)
2-8 μ INCHES GOLD OVER 150-250 μ INCHES NICKEL

0.062" +/-0.006



LAYER 1 TOP
LAYER 2
LAYER 3
LAYER 4 BOTTOM

LAYER STACKUP
SCALE: NONE

 freescale <small>SEMICONDUCTOR</small>	Project Name: XXXXXXXXXXXXX
	H/W PN: S1FXXXXX-XXXX
L1_TOP	FABRICATION

[illegible]